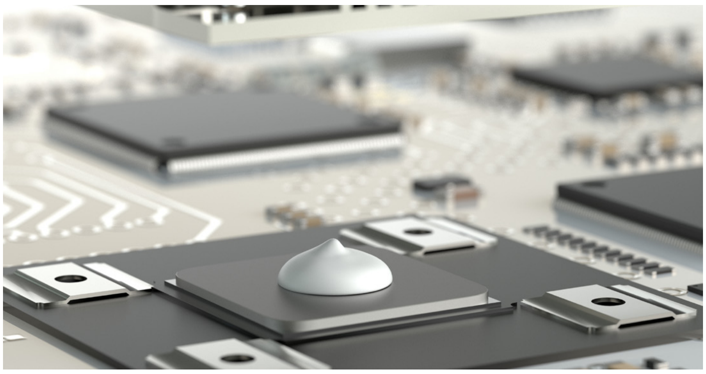
LOCTITE®

BERGQUIST®

LOSING THE HEAT AND *RAISING 5G MOBILE PERFORMANCE*

LOCTITE® BERGQUIST® LIQUI FORM TLF 6000HF

LOCTITE® BERGQUIST® LIQUI FORM TLF 6000HF is a one-part, pre-cured gel thermal interface material (TIM) designed for the demands of mass production and the performance expectations of 5G mobile devices.



The silicone-based TIM has high thermal conductivity of 6.0 W/m-K to effectively dissipate operational heat from processing ICs, reducing the opportunity for thermal events that can adversely impact function. In addition, the good electrical properties (high volume and surface resistivity) of LOCTITE® BERGQUIST® LIQUI FORM TLF 6000HF ensure proper operation of ICs where the material is used as the TIM between the component and EMI housing. Low stress and high performance, LOCTITE® BERGQUIST® LIQUI FORM TLF 6000HF brings an innovative thermal solution to the consumer electronics sector.

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Key Features

- High thermal conductivity of > 6.0 W/m-K (6.72 W/m-K as tested)
- Fast flow rate of 13.7 g/minute (average, 1.2 mm dispensing needle)
- Good, consistent dispensing performance
- Good electrical performance, high volume resistance of 3E12 Ω.cm and high surface resistance of 2E12 Ω.cm
- Gap stability in application
- Low assembly stress

Key Benefits

- Enables high volume manufacturing
- Enhances 5G device reliability
- Reduces stress on high-value components during application
- Compatible with various types of dispensing equipment
- Simplifies storage and processing, no mixing required

Key Applications

- 5G mobile devices
- Telecommunications
- Computing
- Consumer electronics

TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity, TA DHR3, PP25 cone @ 25°C, mPa·s (cP):	
1 mm gap @ Shear rate 1 s^{-1}	696,000
Density, ASTM D792, g/cc	3.4
Flow Rate @ 90 psi, g/min:	
30cc EFD	108.7
30cc EFD with 1.2 mm needle	13.7

TYPICAL PROPERTIES OF CURED MATERIAL

PHYSICAL PROPERTIES	
Siloxane Content, ΣD3-D10, ppm	80
THERMAL PROPERTIES	
Thermal Conductivity, ASTM D5470, W/(m-K)	6.72
ELECTRICAL PROPERTIES	
Volume Resistivity, ASTM D257, ohm-cm	3×10^{12}
Surface Resistivity, ASTM D257, ohms	2×10^{12}

Want a reliable, stable thermal solution that cools mobile ICs and raises performance?
Get in touch with a Henkel TIM technical specialist.

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